



CMP PAD CONDITIONING



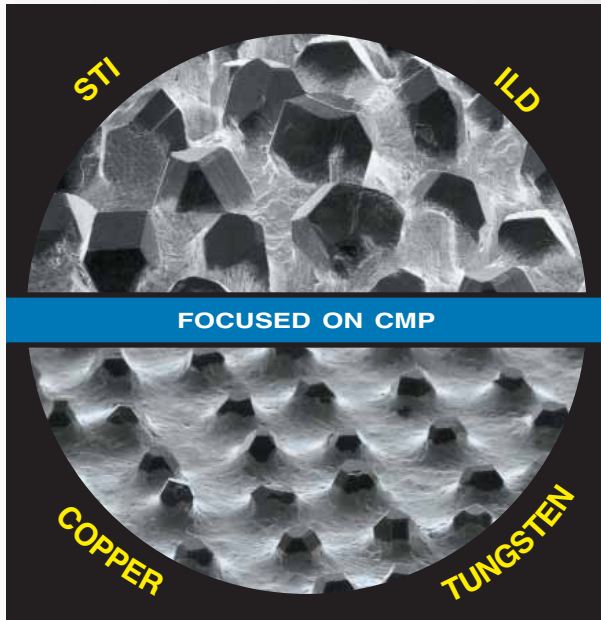
abrasive
technology

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Setting the global standards for superabrasive tooling™

ATI'S INNOVATION, TECHNOLOGY AND EXPERTISE DRIVE DOWN OUR CUSTOMERS' COST OF OWNERSHIP

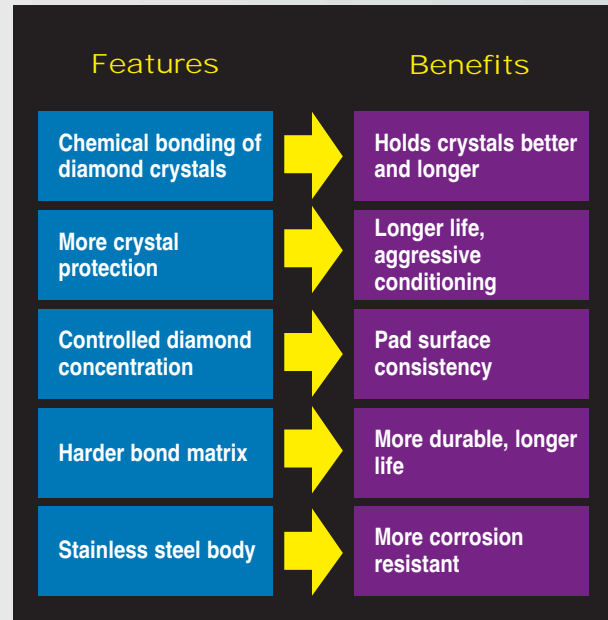
LEADING INNOVATIONS DELIVER BEST IN CLASS CMP PAD CONDITIONING



INDUSTRY EXPERTISE DRIVES FUTURE OPPORTUNITIES

Technical innovation is the name of the game at Abrasive Technology. As the worldwide leader in superabrasive grinding and tooling, Abrasive Technology and its associates are strongly committed to designing, developing and manufacturing state-of-the-art products to meet the challenging needs of the semiconductor industry. With more than 30 years of superabrasive grinding expertise to its credit, the Company believes in a global presence with 10 locations around the globe to meet and ultimately exceed customer expectations.

THE P.B.S.® ADVANTAGE



Abrasive Technology understands that its global customers demand:

- Higher wafer yield
- Performance consistency
- Increased process reliability
- Lowest cost of ownership

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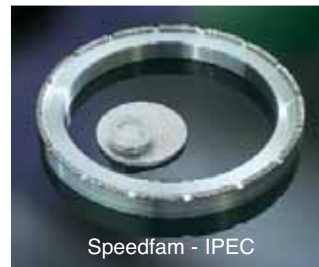
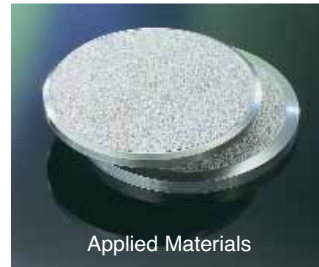


PAD CONDITIONERS FOR ALL CMP PLATFORMS

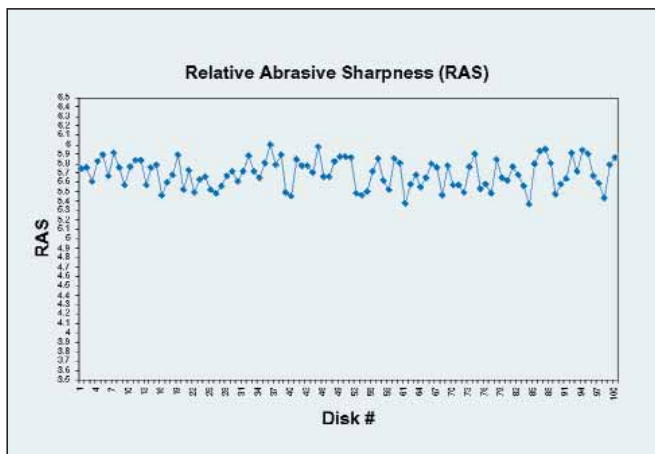
CMP PAD CONDITIONING

Abrasive Technology's pad conditioning disks operate on all major CMP equipment platforms around the world in oxide (ILD, STI, POLY, BPSG) and metal (W, Cu, Ta, Al) processes. Disks are available in both magnetic and non-magnetic grades of stainless steel in a wide variety of front surface configurations. The ability to dial in customers' CMP process requirements allows ATI to deliver conditioning solutions in the shortest possible time.

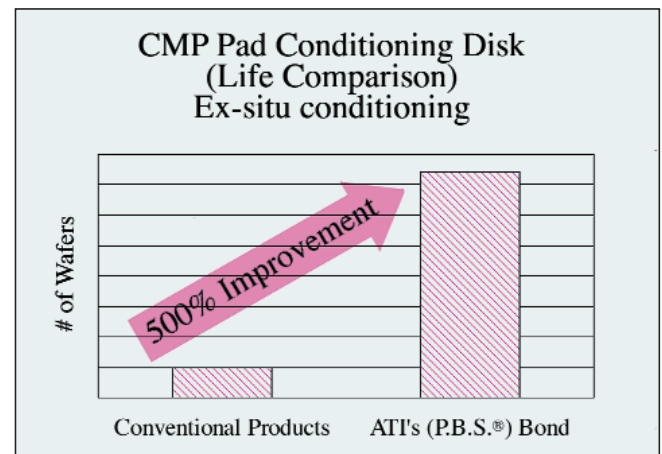
ALSO AVAILABLE: DISKS FOR 300 MM SYSTEMS



PRODUCT CONSISTENCY



COST OF OWNERSHIP



ISO 9001 CERTIFIED



WAFER BACKSIDE GRINDING

Our wafer backside grinding tools positively impact your total cost of ownership through:

- Longer wheel life
- Lack of nitride passivation
- Extremely low depth of sub-surface damage
- Strong, premium quality diamond
- High production up-time
- Extremely high die strength
- Reduced wheel dressing

ATI's wafer backside grinding tools are used for grinding Silicon, Silicon Carbide, Ti-Al Carbide and other challenging substrates in the Okamoto, Disco, Strasbaugh and G&N machines.

MORE INFORMATION

We welcome the opportunity to address your individual questions. You may contact us via e-mail at cmp@abrasive-tech.com or visit our web site at www.abrasive-tech.com.



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